[redacted]

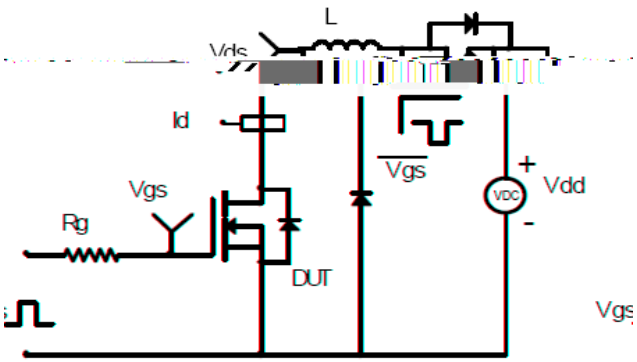
Symbol	Parameter	Max.	Units
I_D @ T_C = 25°C	Continuous Drain Current, V_{GS} @ 10V	180	A
I_D @ T_C = 100°C	Continuous Drain Current, V_{GS} @ 10V	107	
I_{DM}	Pulsed Drain Current	5.12 Tf1 0 0	

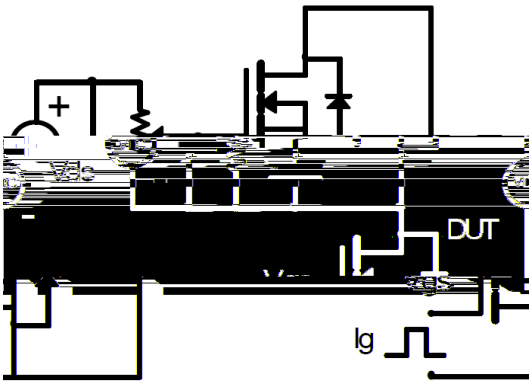
[redacted]

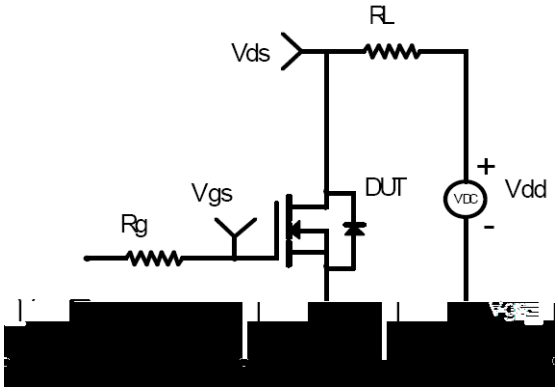
Symbol	Characterizes	Typ.	Max.	Units
	Junction-to-case			

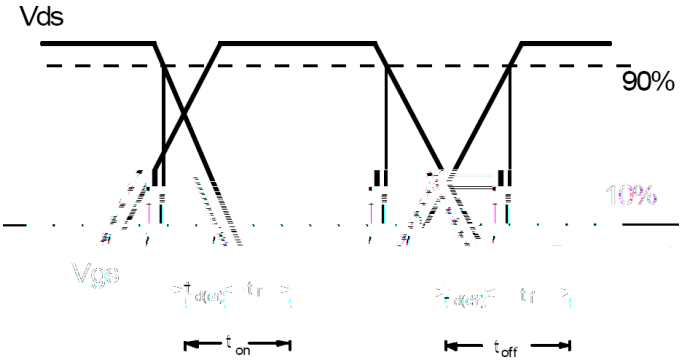
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source breakdown voltage	40			V	V_{GS} = 0V, I_D
$R_{DS(on)}$	Static Drain-to-Source on-resistance		1.6	3	m	V_{GS}=10V,I_D = 40A
$V_{GS(th)}$	Gate threshold voltage	2		4	V	V_{DS} = V_{GS}, I_D
I_{DSS}	Drain-to-Source leakage current			1		V_{DS} = 40V,V_{GS} = 0V
I_{GSS}	Gate-to-Source forward leakage			100	nA	V_{GS} =20V
				-100		V_{GS} = -20V
C_{iss}	Input capacitance		10547		pF	V_{GS} = 0V
C_{oss}	Output capacitance		654			V_{DS} = 30V
C_{rss}	Reverse transfer capacitance		553			1MHz
Q_g	Total gate charge				nC	I_D = 20A,
Q_{gs}	Gate-to-Source charge					V_{DS}=20V,
Q_{gd}	Gate-to-Drain("Miller") charge					V_{GS} = 10V
$t_{d(on)}$	Turn-on delay time				ns	
t_r	Rise time					V_{GS}=10V, V_{DD} =20V,
$t_{d(off)}$	Turn-Off delay time					R_{GEN}=3.6 $_L$=1
t_f	Fall time					

[redacted]

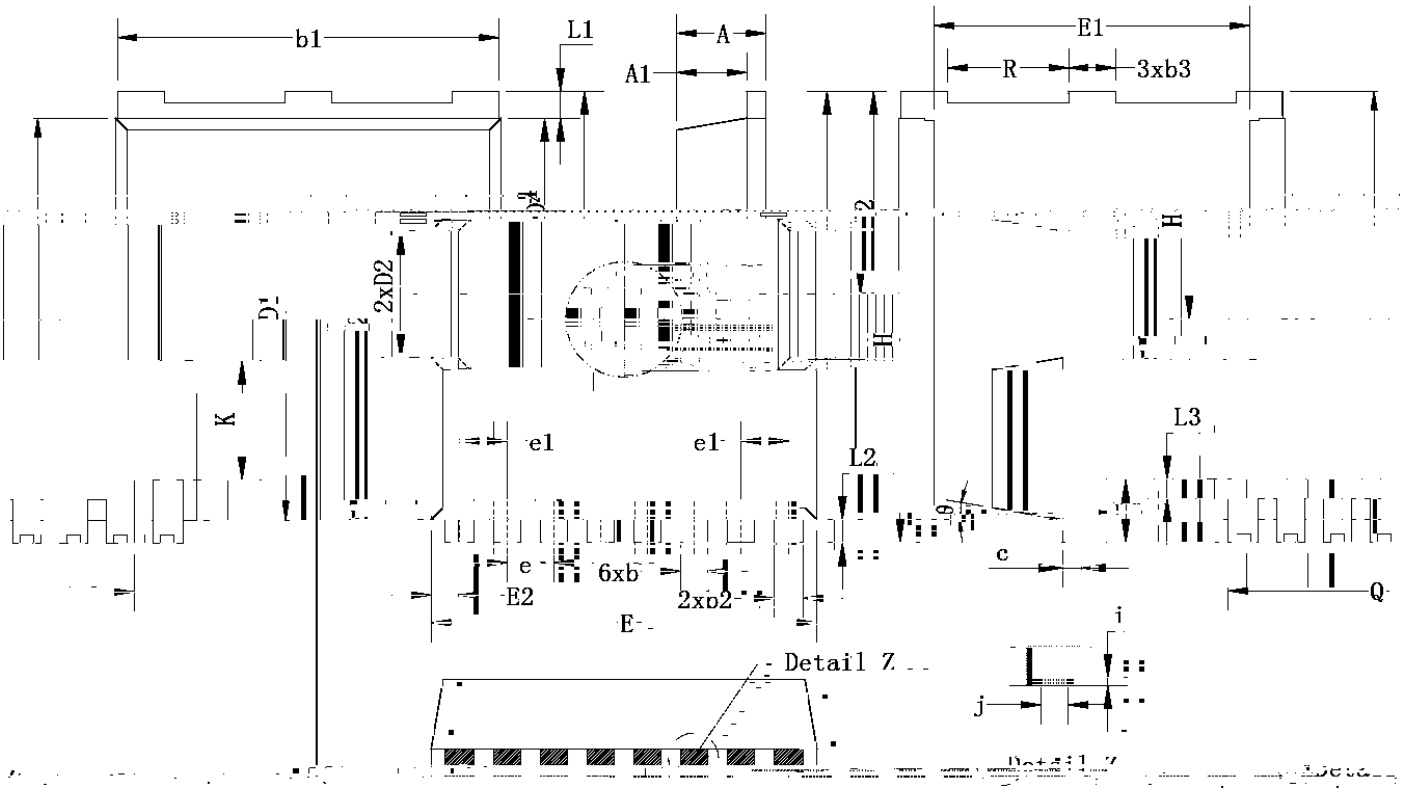








Calculated continuous current based on maximum allowable junction temperature.
Repetitive rating; pulse width limited by max. junction temperature.
The power dissipation P_D is based on max. junction temperature, using junction-to-case thermal resistance.



Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	2.25	2.30	2.35	E2	0.65	0.70	0.75
11.80	A1	1.75	1.80	1.85	II	11.60	11.70
	b	0.65	0.70	0.75	II1		6.95 BSC
	b1	9.75	9.80	9.85	II2		5.90 BSC
	b2	0.70	0.75	0.80	i		0.10 REF
	b3	1.18	1.20	1.28	j		0.35 REF
	3.10 REF		c	0.45	0.50	0.55	K
1.55	1.65	1.75	D	10.38	10.40	10.48	L
10.75	D1	11.00	11.10	11.20	L1	0.65	0.70	0
4.60	D2	3.05	3.10	3.35	L2	0.60	0.65	0
	c		1.20 BSC		Q		7.95 REF	
2.15	e1		1.925 BSC		R	2.05	2.10	2.15
	E1	8.00	8.10	8.20				

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